EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|---|--|---------------------|-----------|------------------|
| L1 | 283 | wafer and (liquid near5 resin) and ((resin\$4 coat\$4 layer\$4 film) with (etch\$4 cut\$4 saw\$4 machin\$4) with laser) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 11:46 |
| L2 | 218 | 1 and ((remov\$4 wash\$4 dissolv\$4) near5 (resin\$4 coat\$4 layer\$4 film)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 11:47 |
| L3 | 28 | 1 and (remov\$4 with (rins\$4, wash\$4 dissolv\$4) near5 (resin\$4 coat\$4 layer\$4 film)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 11:47 |
| L4 | 24 | 3 and (remov\$4 rins\$4 wash\$4 dissolv\$4) with water | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 11:50 |
| L5 | 24 | 4 and (laser with (film layer\$4 coat\$4 resin\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; | OR | ON | 2006/10/20 12:13 |
| | | | IBM_TDB | | | |
| L6 | 20 | 5 and ((semiconductor wafer) with circuit\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 12:11 |
| L7 | 10 | 6 and (laser with (cut\$4 saw\$4 divid\$4)) | US-PGPUB; USPAT; EPO; JPO; -DERWENT; IBM_TDB | ⊕R - | ON | 2006/10/20 12:11 |
| L8 | 11 | 4 and (laser with (film layer\$4 coat\$4 resin\$4) with (cut\$4 saw\$4 divid\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 12:14 |
| L9 | 11 | 4 and (laser with (film layer\$4 coat\$4 resin\$4) with (cut\$4 saw\$4 divid\$4 debris particle particulate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 12:19 |

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| L10 | 115 | (laser with (film coat\$4 resin\$4) with (cut\$4 saw\$4 divid\$4) with | US-PGPUB; USPAT; | OR | ON | 2006/10/20 12:20 |
|-----|-----|--|---|----|----|------------------|
| | | (debris particle particulate)) | EPO; JPO; DERWENT; IBM_TDB | | | |
| L11 | 38 | 10 and ((control\$4 stop\$4 eliminat\$4 reduc\$4) near5 (debris particle particulate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 12:22 |
| L12 | 16 | 11 and (laser with (semiconduct\$4 wafer silicon)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/10/20 12:21 |
| L13 | 4 | 10 and ((control\$4 stop\$4 eliminat\$4 reduc\$4) near5 (debris particle particulate) with resin\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | ÓR | ON | 2006/10/20 12:22 |